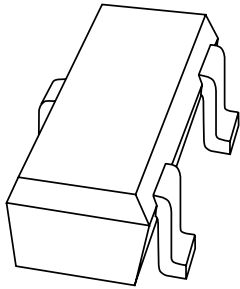


DATA SHEET



1PS181

High-speed double diode

Product data sheet
Supersedes data of April 1996

1996 Sep 03

High-speed double diode

1PS181

FEATURES

- Small plastic SMD package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 80 V
- Repetitive peak reverse voltage: max. 85 V
- Repetitive peak forward current: max. 500 mA.

APPLICATIONS

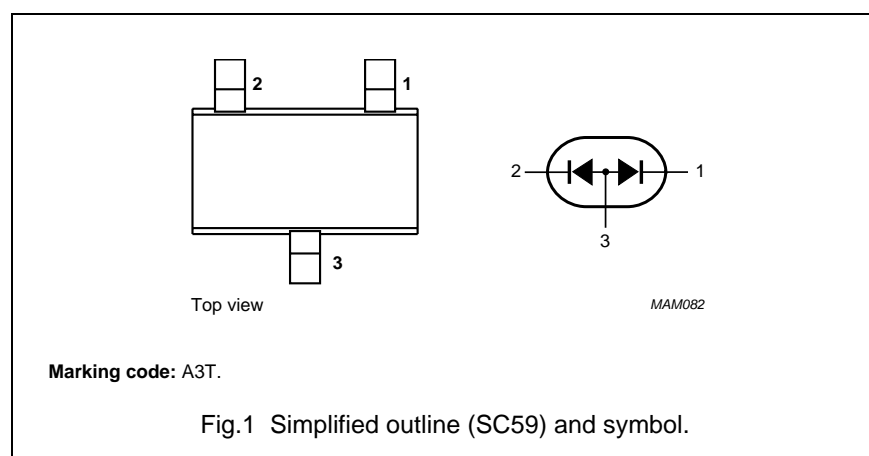
- High-speed switching in e.g. surface mounted circuits.

DESCRIPTION

The 1PS181 consists of two high-speed switching diodes with common anodes, fabricated in planar technology, and encapsulated in the small plastic SMD SC59 package.

PINNING

PIN	DESCRIPTION
1	cathode (k1)
2	cathode (k2)
3	common anode



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V_{RRM}	repetitive peak reverse voltage		–	85	V
V_R	continuous reverse voltage		–	80	V
I_F	continuous forward current	single diode loaded; see Fig.2; note 1	–	215	mA
		double diode loaded; see Fig.2; note 1	–	125	mA
I_{FRM}	repetitive peak forward current		–	500	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j = 25\text{ °C}$ prior to surge			
		$t = 1\text{ }\mu\text{s}$	–	4	A
		$t = 1\text{ s}$	–	0.5	A
P_{tot}	total power dissipation	$T_{amb} = 25\text{ °C}$; note 1	–	250	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C

Note

1. Device mounted on an FR4 printed-circuit board.

High-speed double diode

1PS181

ELECTRICAL CHARACTERISTICS $T_j = 25\text{ °C}$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
Per diode					
V_F	forward voltage	see Fig.3			
		$I_F = 1\text{ mA}$	610	–	mV
		$I_F = 10\text{ mA}$	740	–	mV
		$I_F = 50\text{ mA}$	–	1.0	V
		$I_F = 100\text{ mA}$	–	1.2	V
I_R	reverse current	see Fig.4			
		$V_R = 25\text{ V}$	–	30	nA
		$V_R = 80\text{ V}$	–	0.5	μA
		$V_R = 25\text{ V}; T_j = 150\text{ °C}$	–	30	μA
		$V_R = 80\text{ V}; T_j = 150\text{ °C}$	–	100	μA
C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 0$; see Fig.5	–	2.0	pF
t_{rr}	reverse recovery time	when switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$; $R_L = 100\text{ }\Omega$; measured at $I_R = 1\text{ mA}$; see Fig.6	–	4	ns
V_{fr}	forward recovery voltage	when switched from $I_F = 10\text{ mA}$; $t_r = 20\text{ ns}$; see Fig.7	–	1.75	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-tp}$	thermal resistance from junction to tie-point		250	K/W
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

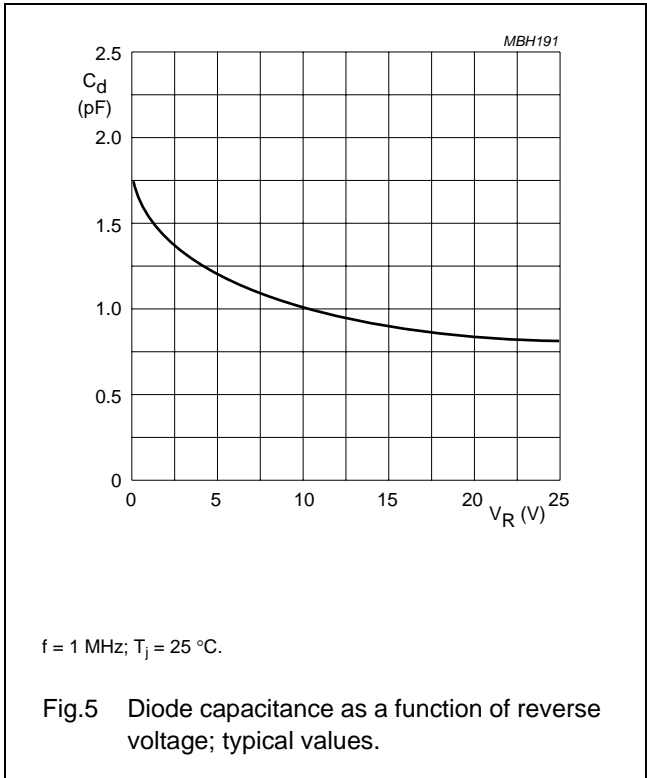
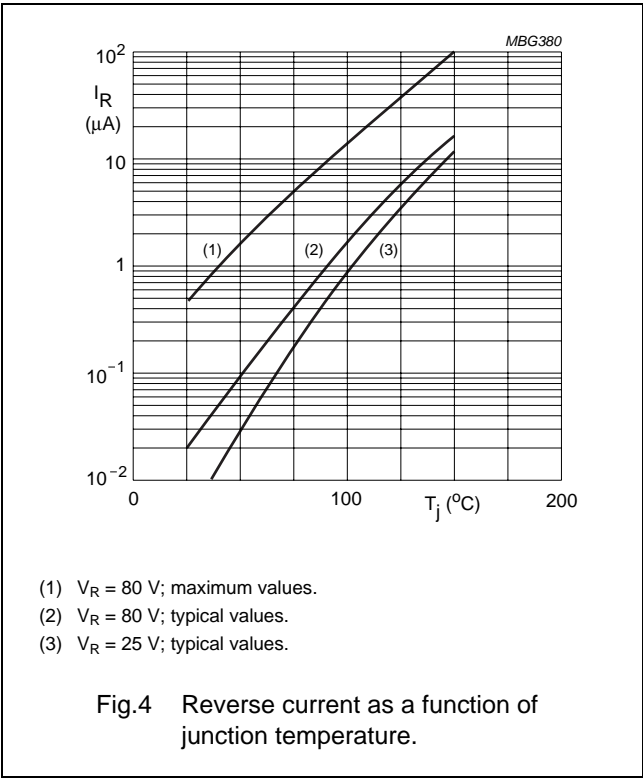
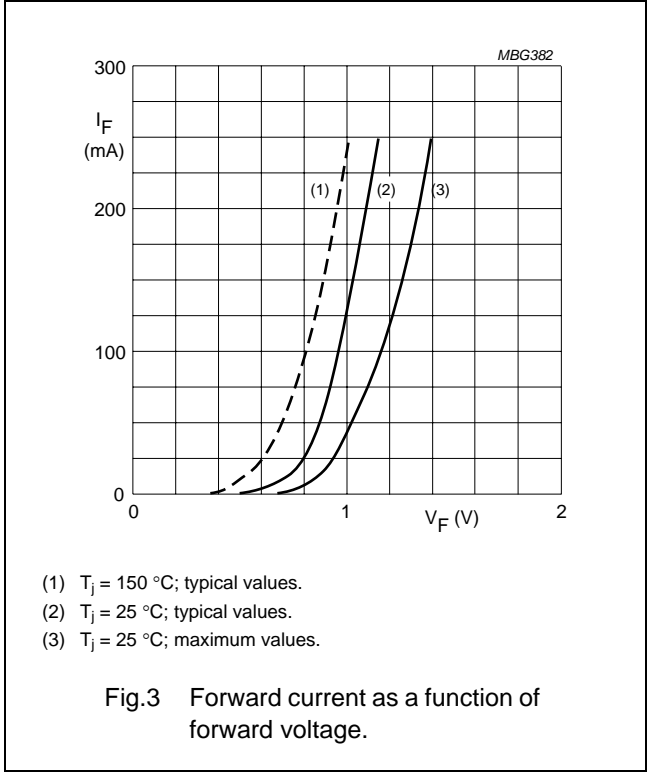
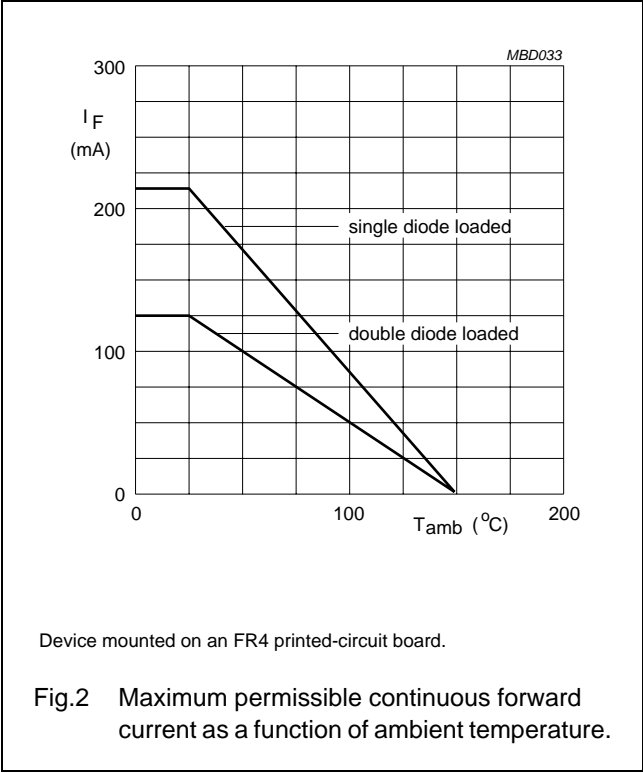
Note

1. Device mounted on an FR4 printed-circuit board.

High-speed double diode

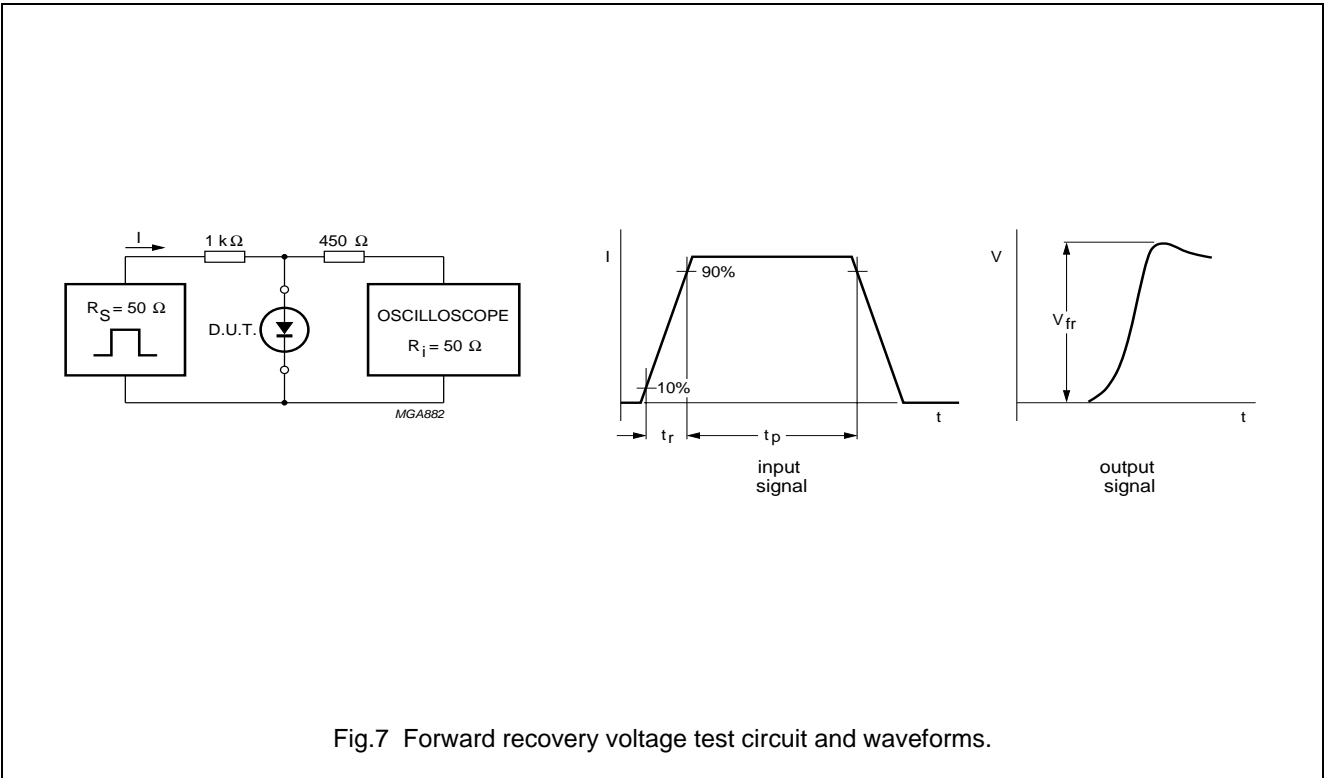
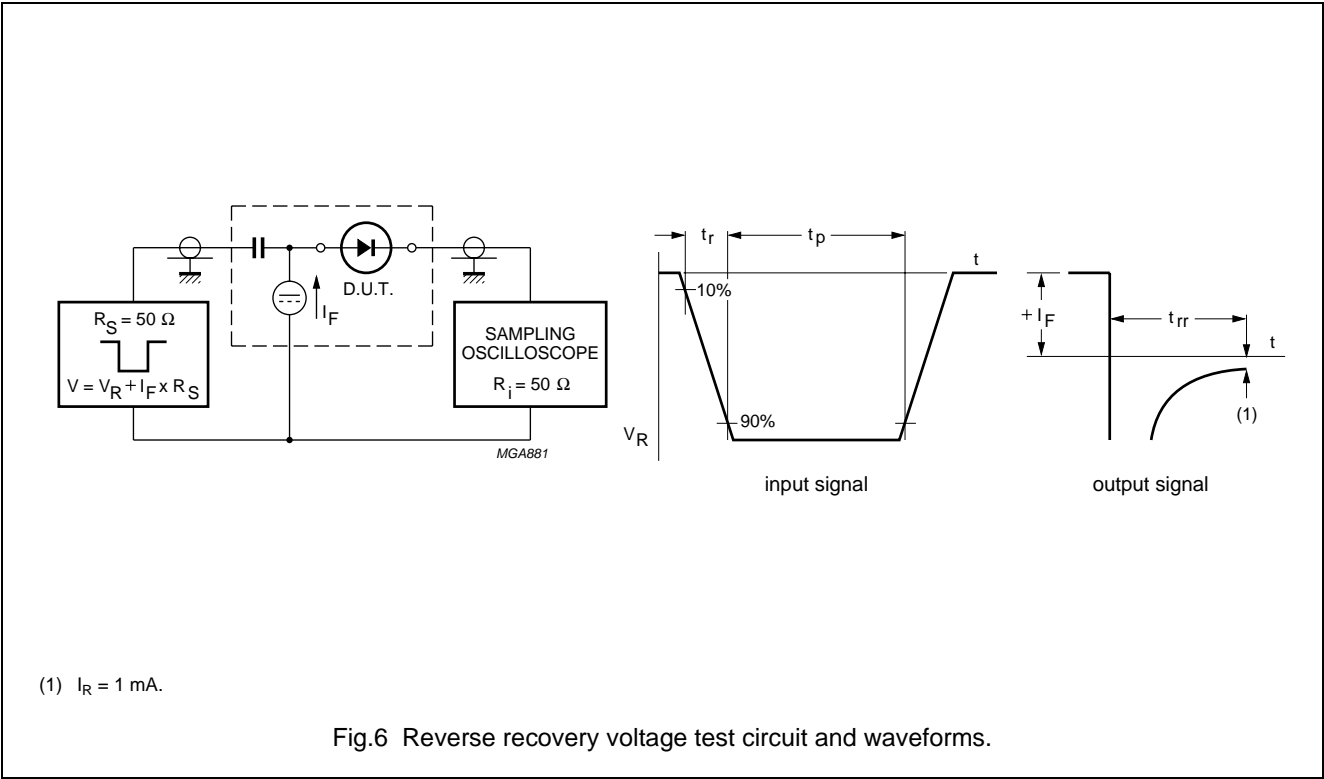
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GRAPHICAL DATA



High-speed double diode

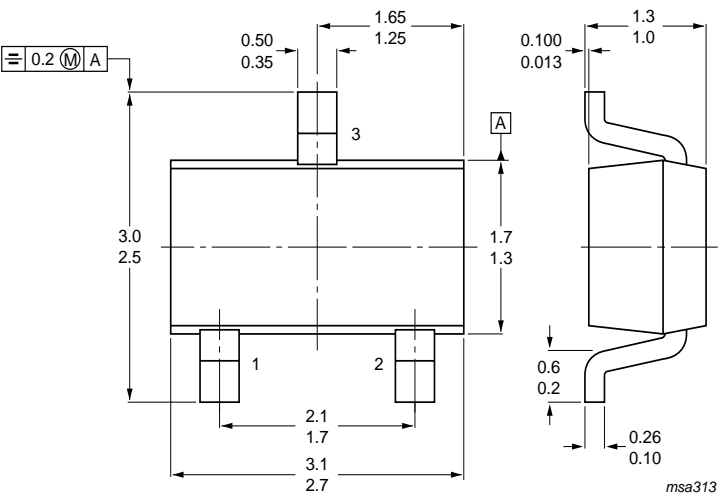
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High-speed double diode

1PS181

PACKAGE OUTLINE



Dimensions in mm.

Fig.8 SC59.

High-speed double diode

1PS181

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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